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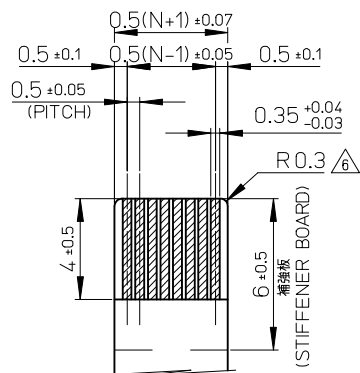
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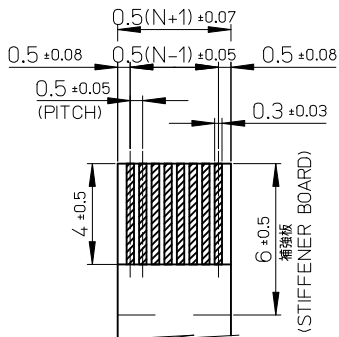
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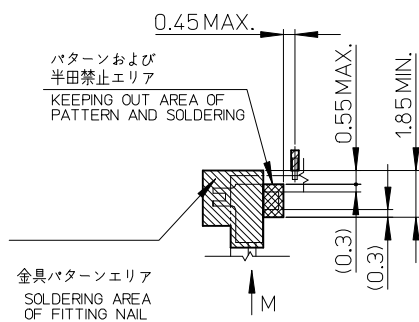
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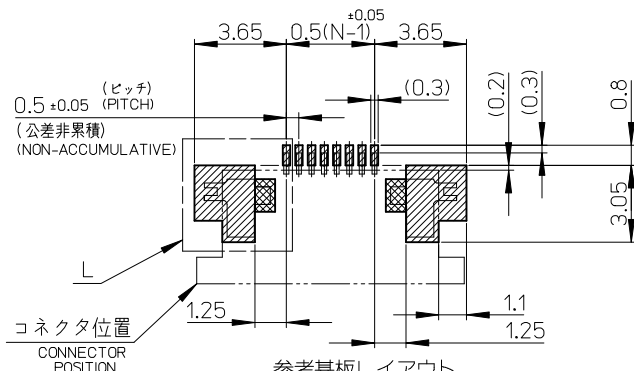
適合銅系めっきFPC推奨寸法
APPLICABLE FPC OF TIN
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3 ± 0.05
THICKNESS: 0.3 ± 0.05/-0.05



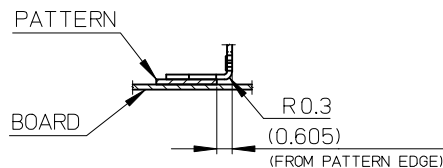
適合銅系めっきFFC推奨寸法
APPLICABLE FFC OF TIN
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3 ± 0.05
THICKNESS: 0.3 ± 0.05/-0.05



DETAIL L



参考基板レイアウト
(マウント面)
RECOMMENDED P.C. BOARD
PATTERN DIMENSION (REF.)
(MOUNTING SIDE)



VIEW M

(DETAIL OF FITTING NAIL
ON PATTERN)

注記NOTES

1.使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ: ポリフェニレンサルフィド (PPS)、ガラス充填、UL94V-0、茶色
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BROWN
ターミナル: リン青銅、ニッケル下地鍍びスズめっき (t=0.2)
TERMINAL: PHOSPHOR BRONZE, TIN BISMUTH OVER NICKEL PLATING
金具: リン青銅、ニッケル下地鍍び (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART
NO.52437-**-26 SHOULD BE LOCKED.

3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、
基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM
DATUM-H.

UPPER DIRECTION: 0.1 MAXIMUM
LOWER DIRECTION: 0.15 MAXIMUM

4. 偶数極に適用

APPLY FOR EVEN CIRCUIT.

5. ハターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6. R0.3は、FPCの導体部にかからないこと

R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7. ソルダータールの平坦度は、0.1MAXIMUMとする。

SOLDER TAIL COPLANARITY IS 0.1 MAXIMUM.

8. ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO.: J2013-1532 DRAWN: NQUE01 CHKD: H11JMA APPR: YNOGAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY YSAKIYAM	DATE '04/01/08	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (BOTTOM CONTACT) TIN-BISMUTH PLATING				
		10 OVER 30 UNDER	± 0.25	CHECKED BY MSASAO	DATE '04/01/08					
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE '04/01/08					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.				SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52437-017				2 OF 2
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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DWG. NO.
SD-52437-018

F

D

V

C

B

DO NOT SCALE DRAWING

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E

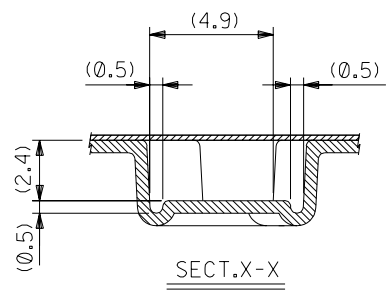
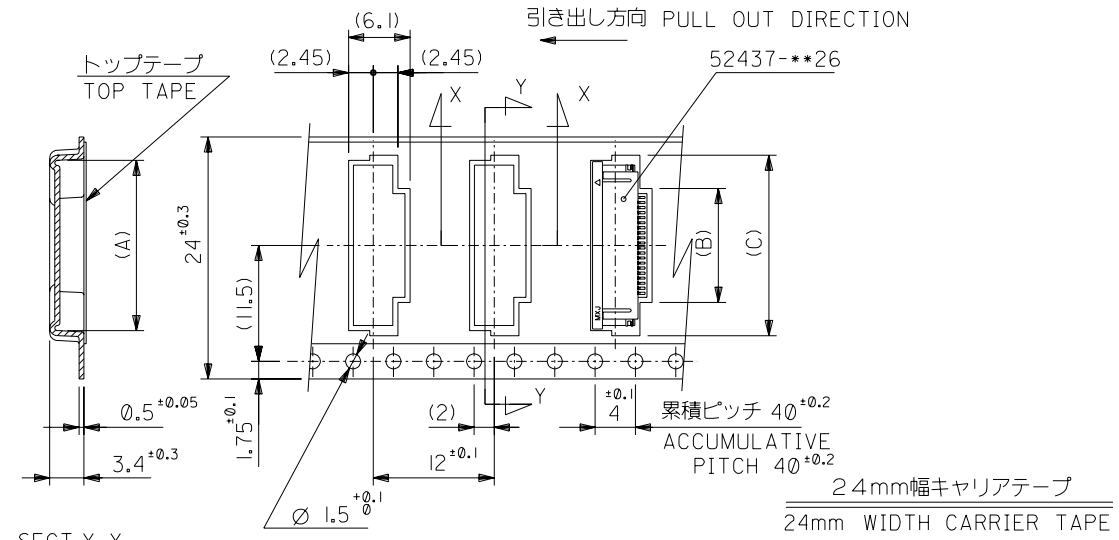
D

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A
SD-52437-018.S02

引き出し方向 PULL OUT DIRECTION



32	37.4	33.4	22.4	15.8	21.4	52437-2972	29
			21.9	15.3	20.9	-2872	28
			21.4	14.8	20.4	-2772	27
			20.9	14.3	19.9	-2672	26
			20.4	13.8	19.4	-2572	25
			19.9	13.3	18.9	-2472	24
			19.4	12.8	18.4	-2372	23
			18.9	12.3	17.9	-2272	22
			17.9	11.3	16.9	-2072	20
			17.4	10.8	16.4	-1972	19
24	29.4	25.4	16.9	10.3	15.9	-1872	18
			16.4	9.8	15.4	-1772	17
			15.9	9.3	14.9	-1672	16
			15.4	8.8	14.4	-1572	15
			14.9	8.3	13.9	-1472	14
			14.4	7.8	13.4	-1372	13
			13.9	7.3	12.9	-1272	12
			13.4	6.8	12.4	-1172	11
			12.9	6.3	11.9	-1072	10
			12.4	5.8	11.4	-0972	9
			11.9	5.3	10.9	-0872	8
			11.4	4.8	10.4	-0772	7
			10.9	4.3	9.9	52437-0672	6
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極致 CIRCUIT

EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	REVISED '04/02/09 EC NO. J2004-2350 DRWN: N.AIDA CH'K: K.TOJO APPR: M.SASAO	RELEASED '04/01/08 EC NO. J2004-1850 DRWN: Y.SAKIYAMA CH'K: M.SASAO APPR: M.SASAO	DESCRIPTION REV	MATERIAL 材料 SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3	FINISH 仕上げ //	WIRE RANGE 適用電線範囲 //	INS. RANGE 被覆外径 //
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GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE //	DESIGN UNITS mm INCH	THIRD ANGLE PROJECTION	DIMENSIONS: mm INCH mm ONLY	SHT REV
10 UNDER 未満	±0.2	DRAWN BY & DATE Y.SAKIYAMA '04/01/08	TITLE: 0.5 FPC Conn Assy ZIF SMT RA With Tape Embstp Pkg -LEAD FREE-		
10 OVER 以上	±0.25	CHECKED BY & DATE M.SASAO '04/01/08			
30 OVER 以上	±0.3	APPROVED BY & DATE M.SASAO '04/01/08			
ANGLE 角度	±3°	CAD FILENAME SD-52437-018.S02			
		MATERIAL NO. 52437-***72	DRAWING NO. SD-52437-018	SHEET NO. 2 OF 3	SIZE B
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			

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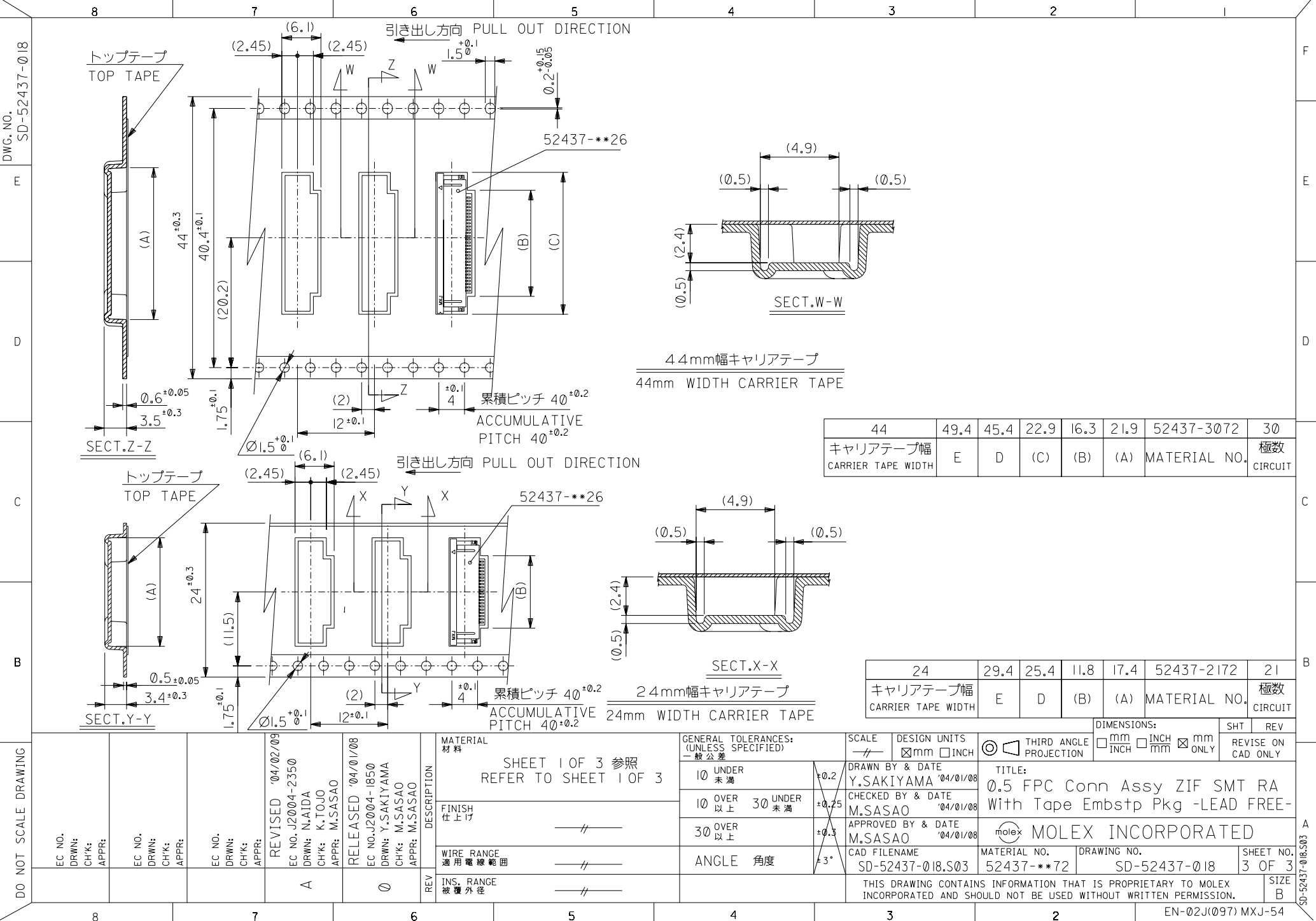
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EN-02J(097) MXJ-54



DWG. NO.
SD-52437-018

F

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V

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DO NOT SCALE DRAWING

EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	REVISED '04/02/09 EC NO. J2004-2350 DRWN: N.AIDA CH'K: K.TOJO APPR: M.SASAO	RELEASED '04/01/08 EC NO. J2004-1850 DRWN: Y.SAKIYAMA CH'K: M.SASAO APPR: M.SASAO	DESCRIPTION REV
			A	Q	
					REV

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 30 UNDER 以上 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

SCALE —//—	DESIGN UNITS ☑mm □INCH	THIRD ANGLE PROJECTION ☉	DIMENSIONS: ☐mm □INCH ☒mm ONLY		SHT REV
DRAWN BY & DATE Y.SAKIYAMA '04/01/08		TITLE: 0.5 FPC Conn Assy ZIF SMT RA With Tape Embstp Pkg -LEAD FREE-			
CHECKED BY & DATE M.SASAO '04/01/08		MOLEX INCORPORATED			
APPROVED BY & DATE M.SASAO '04/01/08					
CAD FILENAME SD-52437-018.S03		MATERIAL NO. 52437-***72	DRAWING NO. SD-52437-018	SHEET NO. 3 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					
SIZE B					

44	49.4	45.4	22.9	16.3	21.9	52437-3072	30
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

24	29.4	25.4	11.8	17.4	52437-2172	21
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

SD-52437-018.S03